

IN THE CLAIMS:

Please amend the claims as shown below. The status of the claims after amendment will be as follows:

1. (currently amended) A lead-free solder alloy ~~comprising~~
consisting of 1.0 - 5.0 wt% Ag, 0.01 - 0.5 wt% Ni, at least one
of (a) 0.001 - 0.05 wt% Co and (b) at least one of P, Ge, and Ga
in a total amount of 0.001 - 0.05 wt%, and a remainder of Sn.

2. (currently amended) A lead-free solder alloy as claimed
in claim 1 ~~which comprises 1.0 - 5.0 wt% Ag, 0.01 - 0.5 wt% Ni,~~
containing 0.001 - 0.05 wt% Co ~~, and a remainder of Sn.~~

3. (currently amended) A lead-free solder alloy as claimed
in claim 1 ~~which comprises 1.0 - 5.0 wt% Ag, 0.01 - 0.5 wt% Ni,~~
containing at least one of P, Ge, and Ga in a total amount of
0.001 - 0.05 wt% ~~, and a remainder of Sn.~~

4. (currently amended) A lead-free solder alloy as claimed
in claim 1 ~~which comprises 1.0 - 5.0 wt% Ag, 0.01 - 0.5 wt% Ni,~~
containing 0.001 - 0.05 wt% Co ~~[[,]]~~ and at least one of P, Ge,
and Ga in a total amount of 0.001 - 0.05 wt% ~~, and a remainder of~~
Sn.

5. (original) A solder ball formed from the alloy of claim
1.

6. (original) A solder paste comprising a solder powder of the alloy according to claim 1 mixed with a flux.

7. (original) A solder bump formed from the alloy of claim 1.

8. (original) An electronic part having a plurality of solder bumps formed from the alloy of claim 1.

9. (original) A method of joining two members comprising a step of forming a soldered joint using the alloy of claim 1.

10. (new) A lead-free solder alloy as claimed in claim 1 containing 0.005 - 0.03 wt% Co.

11. (new) A lead-free solder alloy as claimed in claim 1 containing at least one of P, Ge, and Ga in a total amount of 0.002 - 0.01 wt%.

12. (new) A lead-free solder alloy as claimed in claim 1 containing 0.02- 0.2 wt% Ni.